

MOS FIELD EFFECT TRANSISTOR $\mu PA1856$

P-CHANNEL MOS FIELD EFFECT TRANSISTOR FOR SWITCHING

DESCRIPTION

The μ PA1856 is a switching device which can be driven directly by a 2.5-V power source.

The μ PA1856 features a low on-state resistance and excellent switching characteristics, and is suitable for applications such as power switch of portable machine and so on.

FEATURES

- Can be driven by a 2.5-V power source
- Low on-state resistance $R_{DS(on)1} = 45 \text{ m}\Omega \text{ MAX.}$ (VGs = -4.5 V, ID = -2.5 A) $R_{DS(on)2} = 48 \text{ m}\Omega \text{ MAX.}$ (VGs = -4.0 V, ID = -2.5 A) $R_{DS(on)3} = 72 \text{ m}\Omega \text{ MAX.}$ (VGs = -2.7 V, ID = -2.5 A) $R_{DS(on)4} = 77 \text{ m}\Omega \text{ MAX.}$ (VGs = -2.5 V, ID = -2.5 A)

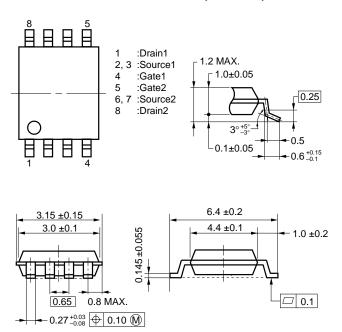
ORDERING INFORMATION

PART NUMBER	PACKAGE
μ PA1856GR-9JG	Power TSSOP8

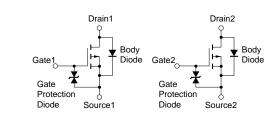
ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Drain to Source Voltage	VDSS	-20	
Gate to Source Voltage	Vgss	∓12	
Drain Current (DC)	D(DC)	∓4.5	
Drain Current (pulse) Note1	D(pulse)	∓18	
Total Power Dissipation Note2	Рт	2.0	
Channel Temperature	Tch	150	
Storage Temperature	Tstg	-55 to +150	,

PACKAGE DRAWING (Unit: mm)



EQUIVALENT CIRCUIT



Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1%

- 2. Mounted on ceramic substrate of 5000 mm² x 1.1 mm
- **Remark** The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

V

V A

А

W

°C

°C

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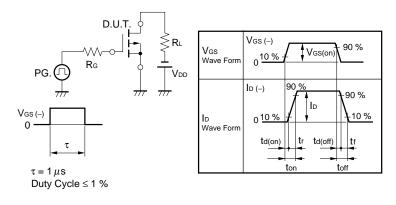
D13808EJ3V0DS00 (3rd edition) May 2001 NS CP(K) The mark **★** shows major revised points.

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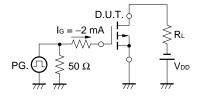
ELECTRICAL CHARACTERISTICS (TA = 25°C)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	loss	$V_{DS} = -20 V$, $V_{GS} = 0 V$			-10	μA
Gate Leakage Current	lgss	$V_{GS} = \pm 12 V$, $V_{DS} = 0 V$			∓10	μA
Gate Cut-off Voltage	V _{GS(off)}	$V_{DS} = -10 V$, $I_D = -1 mA$	-0.5	-1.1	-1.5	V
Forward Transfer Admittance	y _{fs}	$V_{DS} = -10 V$, $I_D = -2.5 A$	3	8.8		s
Drain to Source On-state Resistance	RDS(on)1	$V_{GS} = -4.5 \text{ V}, \text{ Id} = -2.5 \text{ A}$		37	45	mΩ
	RDS(on)2	$V_{GS} = -4.0 \text{ V}, \text{ ID} = -2.5 \text{ A}$		39	48	mΩ
	RDS(on)3	$V_{GS} = -2.7 \text{ V}, \text{ Id} = -2.5 \text{ A}$		52	72	mΩ
	RDS(on)4	$V_{GS} = -2.5 V$, $I_D = -2.5 A$		57	77	mΩ
Input Capacitance	Ciss	V _{DS} = -10 V		700		pF
Output Capacitance	Coss	Vgs = 0 V		208		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		100		pF
Turn-on Delay Time	td(on)	$V_{DD} = -10 V$		300		ns
Rise Time	tr	ID = -2.5 A		528		ns
Turn-off Delay Time	td(off)	V _{GS} = -4.0 V		242		ns
Fall Time	tr	R _G = 10 Ω		698		ns
Total Gate Charge	Q _G	$V_{DS} = -16 V$		6.0		nC
Gate to Source Charge	Q _{GS}	I⊳ = −4.5 A		2.1		nC
Gate to Drain Charge	Qgd	V _{GS} = -4.0 V		2.8		nC
Diode Forward Voltage	VF(S-D)	IF = 4.5 A, VGS = 0 V		0.86		V
Reverse Recovery Time	trr	IF = 4.5 A, VGS = 0 V		32		ns
Reverse Recovery Charge	Qrr	di/dt = $10 \text{ A}/\mu \text{s}$		2.2		nC

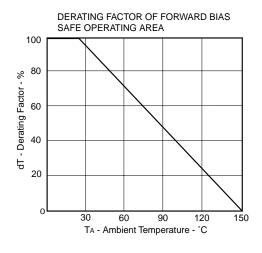
TEST CIRCUIT 1 SWITCHING TIME

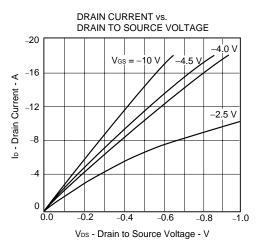


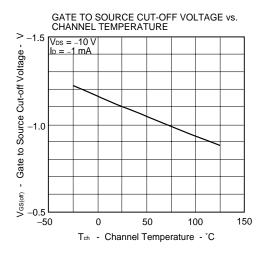
TEST CIRCUIT 2 GATE CHARGE

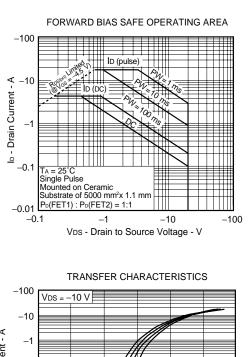


TYPICAL CHARACTERISTICS (TA = 25°C)

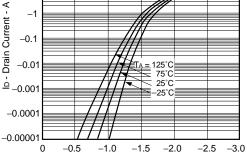






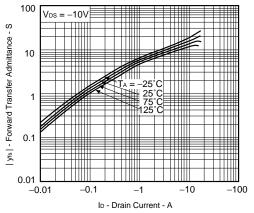


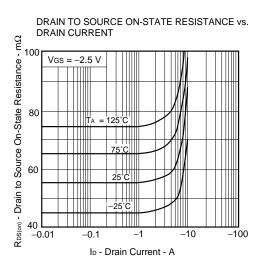
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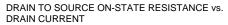


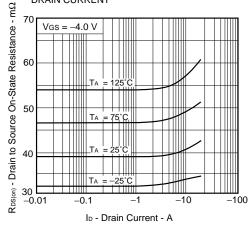
Vgs - Gate to Sorce Voltage - V

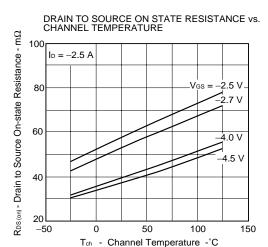
FORWARD TRANSFER ADMITTANCE Vs. DRAIN CURRENT

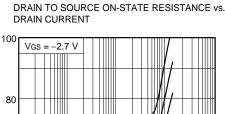


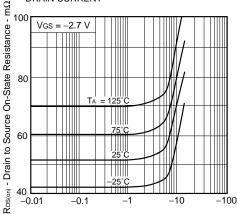


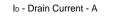




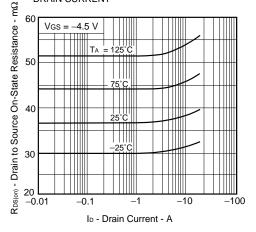




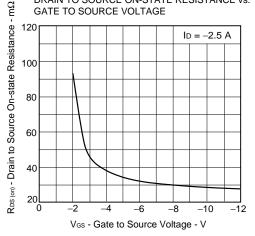




DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT

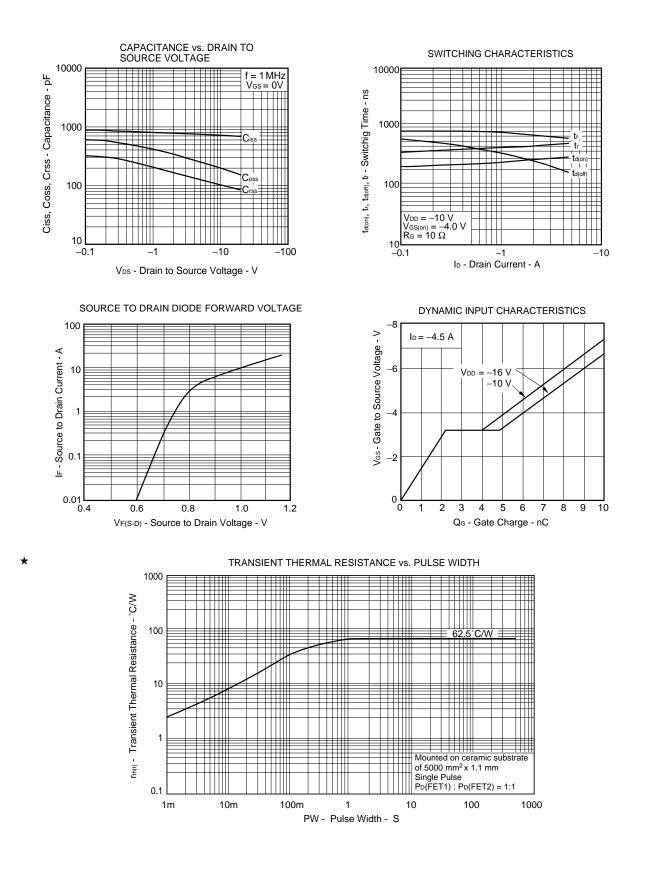


DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



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Data Sheet D13808EJ3V0DS



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